

12V P-CHANNEL ENHANCEMENT MODE MOSFET

Summary

V _{(BR)DSS}	R _{DS(on)} max	I _D max
-12V	$29m\Omega @V_{GS} = -4.5V$	-6.6 A
	$45m\Omega @V_{GS} = -2.5V$	-5.3 A
	60mΩ @V _{GS} = -1.8V	-4.6 A
	100mΩ @V _{GS} = -1.5V	-3.5 A

Applications

This device provides high performance, low $R_{DS(ON)}$ P Channel MOSFETs in the thermally and space efficient X1-DFN1616-6 package. The low $R_{DS(ON)}$ of this MOSFET ensures conduction losses are kept making it ideal for use as a:

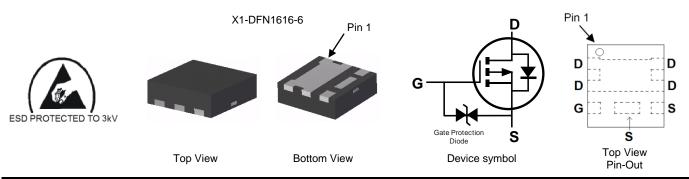
- Battery Disconnect Switch
- Load Switch for Power Management Functions

Features and Benefits

- Typical off board profile of 0.5mm ideally suited for thin applications
- Low R_{DS(ON)} minimizes conduction losses
- PCB footprint of 2.56mm²
- 3kV ESD Protected Gate protection against human borne ESD
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X1-DFN1616-6
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Lead Free Plating (NiPdAu Finish over Copper Leadframe)
- Terminals: Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.04 grams (Approximate)



Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMP1245UFCL-7	P5	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information





P5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Y = 2011) M = Month (ex: 9 = September)

Date Code Key

Year	2011		20	14	2015	2016	2017	2018	20	19	2020	2021
Code	Y		E	3	С	D	Е	F	(3	Н	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C unless otherwise specified.)

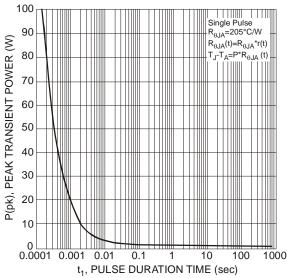
Characteristic		Symbol	Value	Units
Drain-Source Voltage		V _{DSS}	-12	V
Gate-Source Voltage		V _{GSS}	±8	V
Continuous Drain Current (Note 6)	@T _A = +25°C @T _A = +70°C	I _D	-6.6 -5.25	А
Pulsed Drain Current	$T_{P} = 10 \mu s$	I _{DM}	-16.67	А

Thermal Characteristics (@T_A = +25°C unless otherwise specified.)

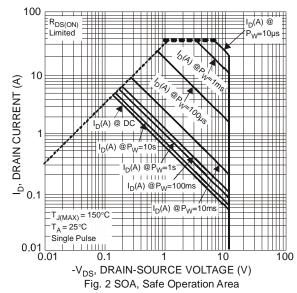
Characteristic	Symbol	Value	Units	
Total Power Dissipation	(Note 5)	D	613	mW
Total Fower Dissipation	(Note 6)	P _D	1.7	W
Thermal Resistance, Junction to Ambient	(Note 5)	0	204	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{\theta JA}$	74	C/VV
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

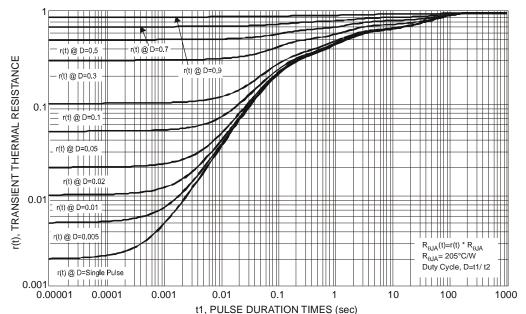
Notes:

- 5. For a device surface mounted on minimum recommended pad layout, in still air conditions; the device is measured when operating in a steady state condition.
- 6. For a device surface mounted on 25mm by 25mm by 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady state condition.











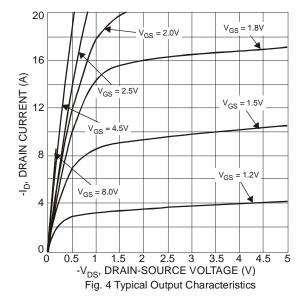
Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

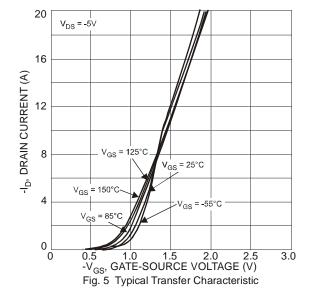
Characteristic	Symbol	Min	Тур	Max	Unit	Test C	ondition
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-12	_	_	V	$V_{GS} = 0V, I_D =$	-250µA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1	μΑ	V _{DS} = -12.0V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 8.0 \text{V}, V_{DS} = 0 \text{V}$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(th)}	-0.3	-0.6	-0.95	V	$V_{DS} = V_{GS}, I_D =$	= -250µA
		1	25	29		$V_{GS} = -4.5V, I_{D}$) = - 4A
Static Drain-Source On-Resistance	D	_	31	45	mΩ	$V_{GS} = -2.5V, I_{D}$	e - 3.5A
Static Dialii-Source Off-Resistance	R _{DS} (ON)	_	40	60	11177	$V_{GS} = -1.8V, I_{D}$) = - 1A
		_	60	100		V _{GS} = -1.5 V, I _D = - 0.5A	
Forward Transfer Admittance	Y _{fs}	0.4	3	-	S	$V_{DS} = -5V, I_{D} = -2A$	
Diode Forward Voltage	V _{SD}	-	-	-1.0	V	$V_{GS} = 0V, I_{D} = -2A$	
DYNAMIC CHARACTERISTICS (Note 8)					•	•	
Input Capacitance	C _{iss}	-	1357.4	-	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz	
Output Capacitance	Coss	-	499	-	pF		
Reverse Transfer Capacitance	Crss	-	273.6	-	pF		
Gate Resistance	R_{g}	-	14.26	-	Ω	$V_{DS} = 0V, V_{GS}$	= 0V, f = 1MHz
Total Gate Charge	0	-	16.1	-	nC	$V_{GS} = -4.5V$	
Total Gate Charge	Qg	-	26.1	-	nC		$I_D = -1A$,
Gate-Source Charge	Q_{gs}	-	1.71	-	nC	$V_{GS} = -8V$	$V_{DS} = -10V$
Gate-Drain Charge	Q_{gd}	-	20.48	-	nC		
Turn-On Delay Time	t _{D(on)}	-	15.2	-	ns		
Turn-On Rise Time	t _r	-	33.11	-	ns	$V_{GS} = -2.5V, V_{DS} = -10V$ $I_{D} = -180\text{mA}, R_{G} = 2.0\Omega,$	
Turn-Off Delay Time	t _{D(off)}	-	219.4	-	ns		
Turn-Off Fall Time	t _f	-	217.64	-	ns		

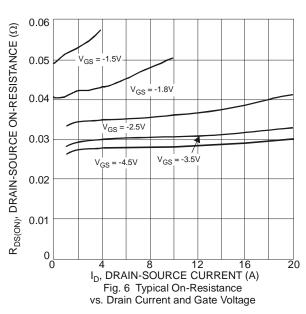
Notes:

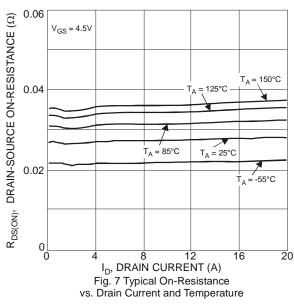
- 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing.

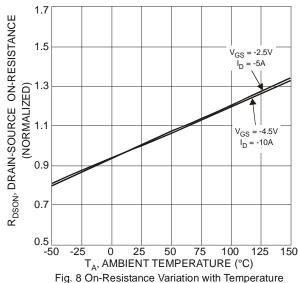












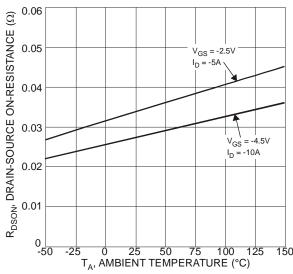


Fig. 9 On-Resistance Variation with Temperature



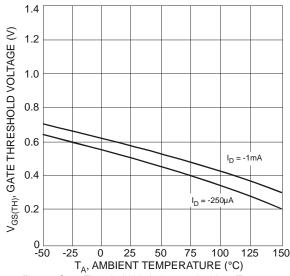


Fig. 10 Gate Threshold Variation vs. Ambient Temperature

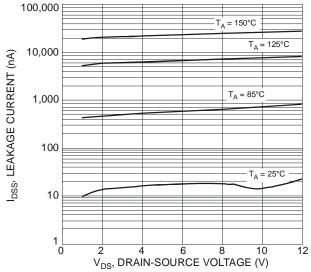
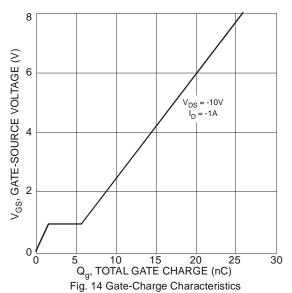
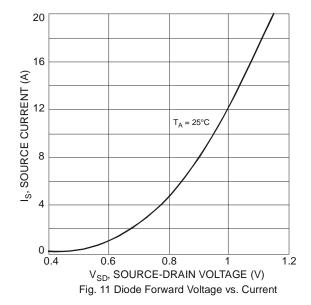
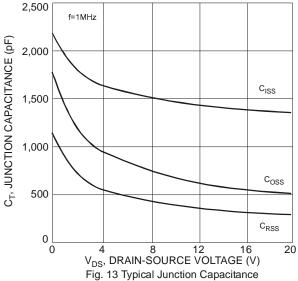


Fig. 12 Typical Drain-Source Leakage Current vs. Voltage



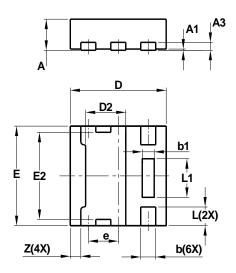






Package Outline Dimensions

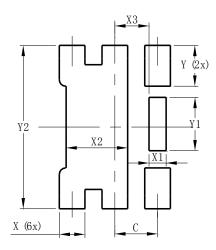
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



X1-DFN1616-6							
Type E							
Dim	Min	Min Max T					
Α	0.47	0.53	0.50				
A1	0	0.05	0.02				
А3		-	0.13				
b	0.20	0.30	0.25				
b1	0.10	0.30	0.20				
D	1.55	1.65	1.60				
D2	0.57	0.77	0.67				
Е	1.55	1.65	1.60				
E2	1.30	1.50	1.40				
е	_	_	0.50				
L	0.25	0.35	0.30				
L1	0.52	0.72	0.62				
Z	_	_	0.175				
All [Dimens	ions in	mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
С	0.500
Х	0.300
X1	0.200
X2	0.720
Х3	0.400
Υ	0.475
Y1	0.620
Y2	1 900

March 2015

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